# US2A THRU US2N

#### SURFACE MOUNT HIGH EFFICIENCY RECTIFIER **REVERSE VOLTAGE** 50 to 1000 Volts **FORWARD CURRENT** 2.0 Ampere

#### **FEATURES**

Plastic package has UL flammability Classification 94V-0 Glass Passivated chip junction Built in strain relief Fast switching speed for high efficiency High temperature soldering guaranteed: 250°C/10 seconds

#### **MECHANICAL DATA**

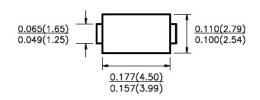
Case: JEDED DO-214AC transfer molded plastic

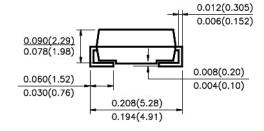
Terminals: Solder plated, Solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

#### DO-214AC (SMA)





#### **MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified, Dimensions in inches and (millimeters) Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load derate current by 20%

PARAMETER		SYMBOL	US2A	US2B	US2D	US2G	US2J	US2K	US2M	UNIT
Maximum Repetitive Peak Reverse Voltage		$V_{RRM}$	50	100	200	400	600	800	1000	VOLTS
Maximum RMS Voltage		V <sub>RMS</sub>	35	70	140	280	420	560	700	VOLTS
Maximum DC Blocking Voltage		V <sub>DC</sub>	50	100	200	400	600	800	1000	VOLTS
Maximum Average Forward Rectified Current At $T_L = 90^{\circ}$ (NOTE 1)		I <sub>(AV)</sub>	2.0							Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)		IFSM	50						Amps	
Maximum instantaneous forward voltage at 2.0A		V <sub>F</sub>	1.0 1.3 1.7					VOLTS		
Maximum DC Reverse Current at Rated DC blocking voltage	T <sub>A</sub> =25℃		5.0							- uA
	T <sub>A</sub> =125℃	- I <sub>R</sub>	100							
Maximum Reverse Recovery Time Test conditions I <sub>F</sub> =0.5A, I <sub>R</sub> =1.0A, I <sub>RR</sub> =0.25A		t <sub>rr</sub>		50		75				ns
Typical Junction Capacitance(Measured at 1.0MHz and applied reverse voltage of 4.0V)		CJ		50		30				pF
Typical Thermal Resistance (NOTE 1)		RөJA	50							°C/W
		Røjl	17							
Operating Junction Temperature		TJ	-55 to +150							$^{\circ}$ C
Storage Temperature Rang		Тѕтс	-55 to +150							$^{\circ}$ C
1. Thermal resistance from Junction to empire and from junction to load mounted on D.C.B. with 0.2 v. 0.2" (5.0 v. 5.0 mm)										\

<sup>1-</sup> Thermal resistance from Junction to ambient and from junction to lead mounted on P.C.B. with  $0.2 \times 0.2''$  (5.0 × 5.0 mm) copper pad areas.

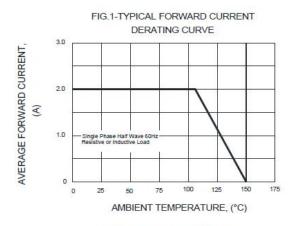
#### Kingtronics ® International Company

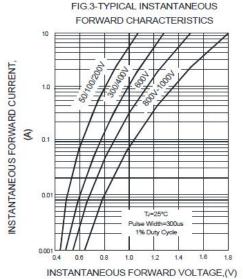
Website: www.kingtronics.com Email: info@kingtronics.com Tel: (852) 8106 7033 Fax: (852) 8106 7099

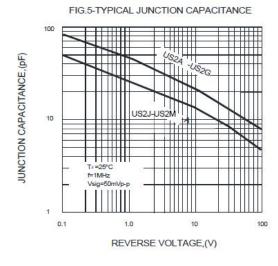
# Kingtronics®

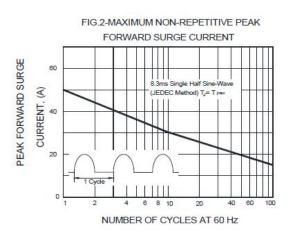
# US2A THRU US2M

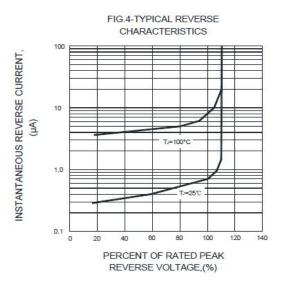
## **RATINGS AND CHARACTERISTIC CURVES**



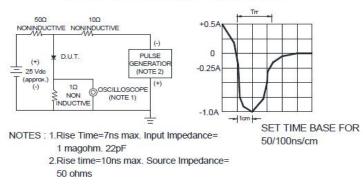












Note: Specifications are subject to change without notice.

### Kingtronics ® International Company

Website: www.kingtronics.com Email: info@kingtronics.com Tel: (852) 8106 7033 Fax: (852) 8106 7099